

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 1.588071**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.007566	1000000	4764.27050781		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.458357	975000	288625		
		Iron (Fe)	7439-89-6	0.011283	24000	7104.84619141		
		Phosphorus (P)	7723-14-0	0.000141	300	88.7869644165		
		Zinc (Zn)	7440-66-6	0.000329	700	207.169570923		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.470110</b>	<b>1000000</b>	<b>296025.8125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.037246	1000000	23453.6210938		
		<b>External Plating Total:</b>				<b>0.037246</b>	<b>1000000</b>	<b>23453.6210938</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.003761	1000000	2368.28198242		
<b>Internal Plating Total:</b>				<b>0.003761</b>	<b>1000000</b>	<b>2368.28198242</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001748	750000	1100.70654297		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000583	250000	367.112060547		
<b>Die Attach Total:</b>				<b>0.002331</b>	<b>1000000</b>	<b>1467.81848145</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.143937	135000	90636.3828125		
		Bromine (Br)	40039-93-8	0.007463	7000	4699.41162109		
		Silica (SiO2)	60676-86-0	0.895608	840000	563959.6875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.013861	13000	8728.19824219		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.005331	5000	3356.90258789		
		<b>Encapsulation Total:</b>				<b>1.066200</b>	<b>1000000</b>	<b>671380.5625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000857	1000000	539.648376465		
					<b>TOTAL MASS (g) :</b>	<b>1.588071</b>		